



Material Content Data Sheet



Sales Product Name				IR38363MTRPBF		Issued		20. July 2018	
MA#				MA001688602					
Package				PG-IQFN-34-900		Weight*		115.24 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.349	1.17	1.17	11703	11703	
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		113		
	non noble metal	zinc	7440-66-6	0.052	0.05		452		
	non noble metal	iron	7439-89-6	1.043	0.90		9047		
wire	non noble metal	copper	7440-50-8	42.333	36.73	37.69	367345	376957	
	noble metal	gold	7440-57-5	0.504	0.44	0.44	4376	4376	
	encapsulation	organic material	carbon black	1333-86-4	0.111	0.10		963	
encapsulation	plastics	epoxy resin	-	5.713	4.96		49573		
	inorganic material	silicondioxide	60676-86-0	49.640	43.09	48.15	430753	481289	
	leadfinish	noble metal	palladium	7440-05-3	0.001	0.00		12	
plating	noble metal	gold	7440-57-5	0.002	0.00		19		
	non noble metal	nickel	7440-02-0	0.041	0.04	0.04	354	385	
	noble metal	palladium	7440-05-3	0.001	0.00		12		
solder	noble metal	gold	7440-57-5	0.002	0.00		20		
	non noble metal	nickel	7440-02-0	0.042	0.04		366		
	noble metal	silver	7440-22-4	0.604	0.52	0.56	5240	5638	
solder	noble metal	silver	7440-22-4	0.051	0.04		440		
	non noble metal	tin	7440-31-5	0.101	0.09		880		
	non noble metal	lead	7439-92-1	1.877	1.63	1.76	16284	17604	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.004	0.00		31		
	non noble metal	zinc	7440-66-6	0.014	0.01		122		
	non noble metal	iron	7439-89-6	0.282	0.24		2449		
	non noble metal	copper	7440-50-8	11.460	9.94	10.19	99446	102048	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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